



INVESTOR CONFERENCE

SCALING THE AI x CONNECTIVITY CONVERGENCE WITH ENGINEERED SUBSTRATES

Barcelona | March 2026

DISCLAIMER

This document is provided by Soitec (the “**Company**”) for information purposes only. The Company’s business operations and financial position are described in the Company’s 2024-2025 Universal Registration Document (which notably includes the Annual Financial Report) and the Company’s 2025-2026 Half-Year Report.

The 2024-2025 Universal Registration Document was filed with the French stock market authority (Autorité des Marchés Financiers, or AMF) on June 11, 2025 and the 2025-2026 Half-Year Report on November 29, 2025. The French version of the 2024-2025 Universal Registration Document and the 2025-2026 Half-Year Report, together with English courtesy translation for information purposes, is available for consultation on the Company’s website (www.soitec.com), in the section Investors - Regulated Information - Financial reports and results & other regulated releases. Your attention is drawn to the risk factors described in Chapter 2.1 (Risk factors and controls mechanism) of the 2024-2025 Company’s Universal Registration Document.

This document contains summary information and should be read in conjunction with the 2024-2025 Universal Registration Document and the 2025-2026 Half-Year Report.

This document contains certain forward-looking statements. These forward-looking statements relate to the Company’s future prospects, developments and strategy and are based on analyses of earnings forecasts and estimates of amounts not yet determinable. By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events and are dependent on circumstances that may or may not materialize in the future. Forward-looking statements are not a guarantee of the Company’s future performance. The occurrence of any of the risks described in Chapter 2.1 (Risk factors and controls mechanism) of the 2024-2025 Universal Registration Document may have an impact on these forward- looking statements. In particular, ongoing geopolitical tensions as well as persistent inflationary pressures, monetary policy and exchange rates uncertainty, and supply chain disruptions, may have consequences that are more significant or longer-lasting than currently anticipated in these forward-looking statements.

Any market shares presented herein are based on internal estimates and relate to that share of the market segment served and addressed by Soitec which may exclude broader segments of the market and competing technologies.

The Company’s actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company’s financial position, results, cash-flows and the developments in the sector in which the Company operates were to conform to the forward- looking statements contained in this document, such elements cannot be construed as a reliable indication of the Company’s future results or developments.

The Company does not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document.

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#01
AI x CONNECTIVITY
CONVERGENCE

#02
ENGINEERED SUBSTRATES
OPPORTUNITIES

#03
SOITEC TECHNOLOGY
LEADERSHIP

01

AI x CONNECTIVITY CONVERGENCE



THE AI x CONNECTIVITY CONVERGENCE IS DRIVING DATA TRAFFIC GROWTH



High-adoption GenAI drives traffic

Widely adopted, data-intensive GenAI apps will drive global mobile network traffic growth



Uplink-driven spectrum expansion

Net-new traffic growth will need network planning and broader band spectrum to support rising uplink needs

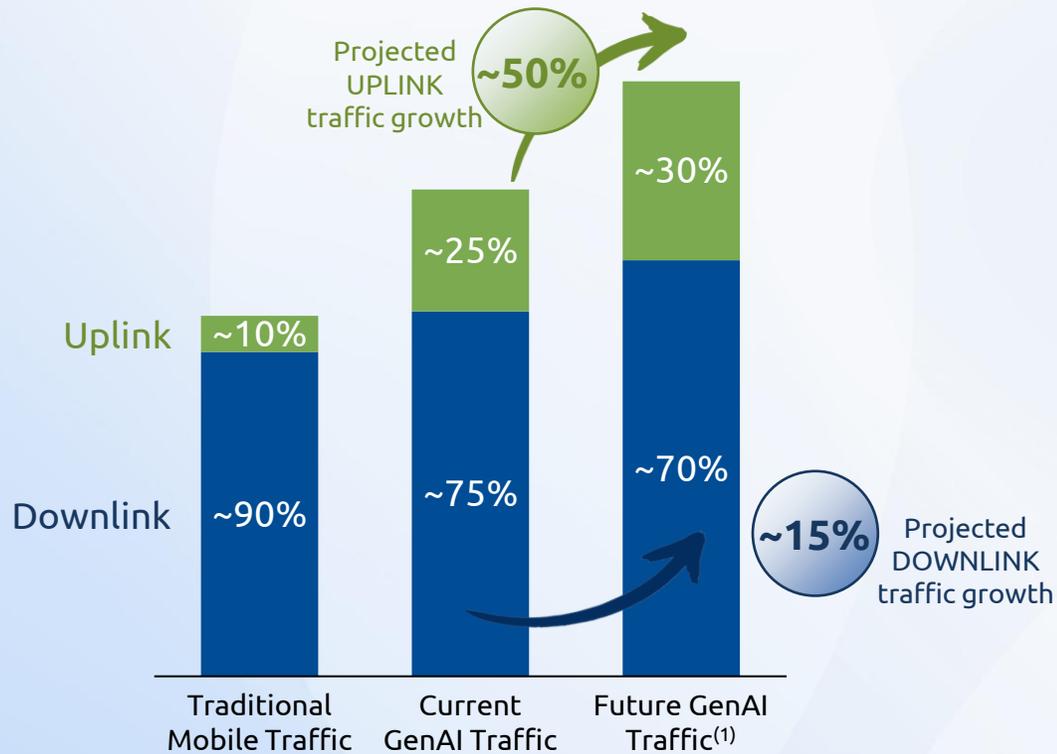


Connectivity enables AI experience

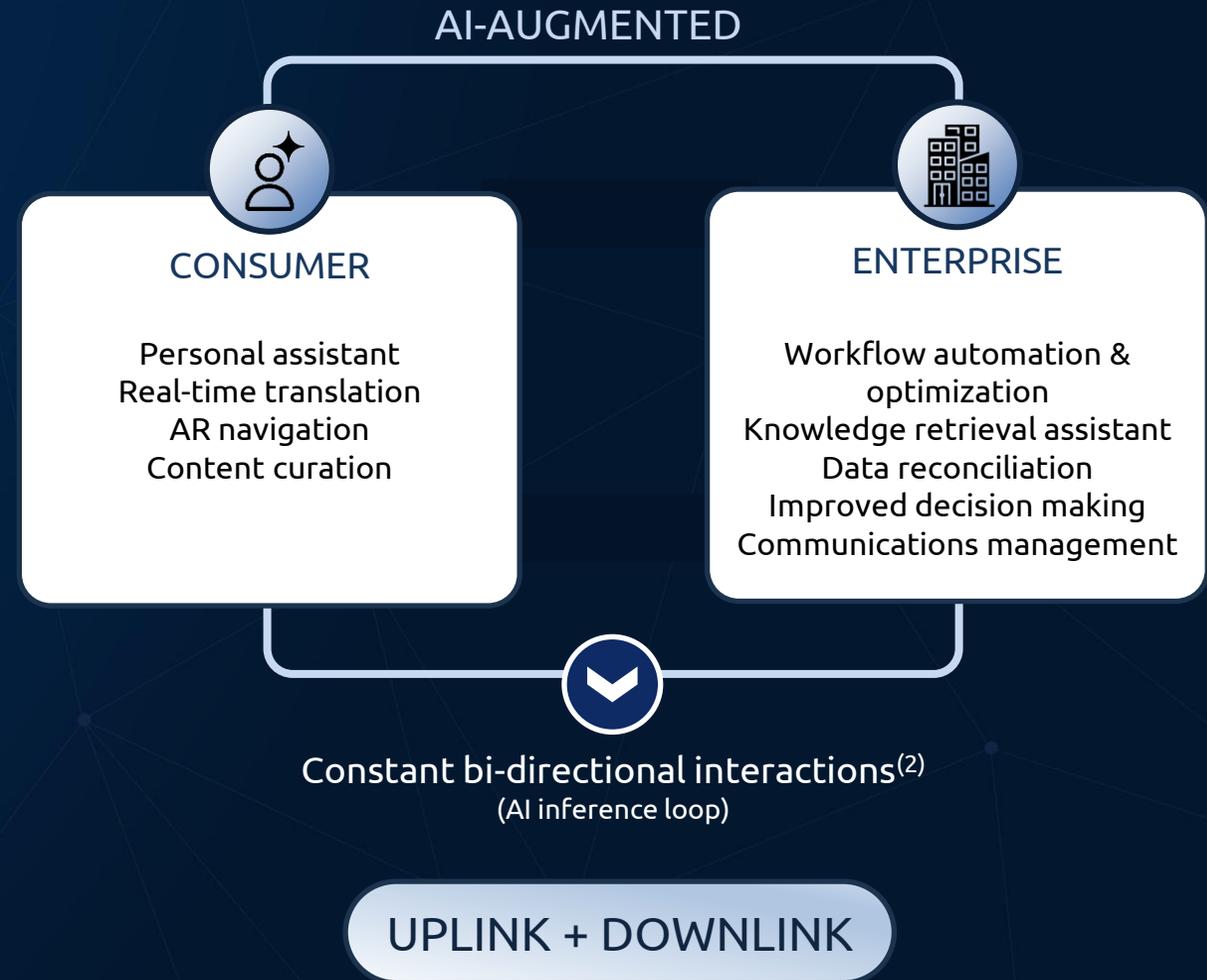
Differentiated connectivity will be crucial to deliver high-quality experiences for personalized AI agents and conversational apps

THE RISE OF GenAI

BOOSTING DEMAND FOR UPLINK AND DOWNLINK TRAFFIC



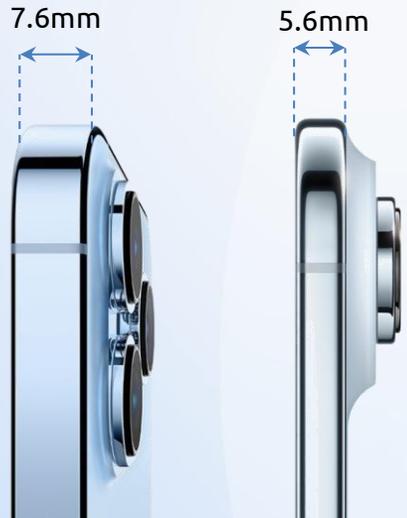
⁽¹⁾ assuming widespread adoption of multimodal AI assistants & AR glasses
 Source: Ericsson Mobility Report 2025, Soitec



⁽²⁾ vs. punctual & user-driven interactions, using mostly downlink, before the AI era

EXTENSION TO NEW FORM FACTORS: SLIMMER, WIDER, MORE CONNECTED

DRIVING NEW REQUIREMENTS AT THE SEMICONDUCTOR LEVEL



Thinner smartphones
iPhone 13 vs iPhone Air 17



Emerging foldable devices
Samsung Z Fold 7



More connected devices
Apple Watch Series 11



Enhanced Wireless functionality
Next-gen AI glasses with 5G connectivity in the branch



POWER, PERFORMANCE, AREA, COST
Key drivers, from systems to substrates

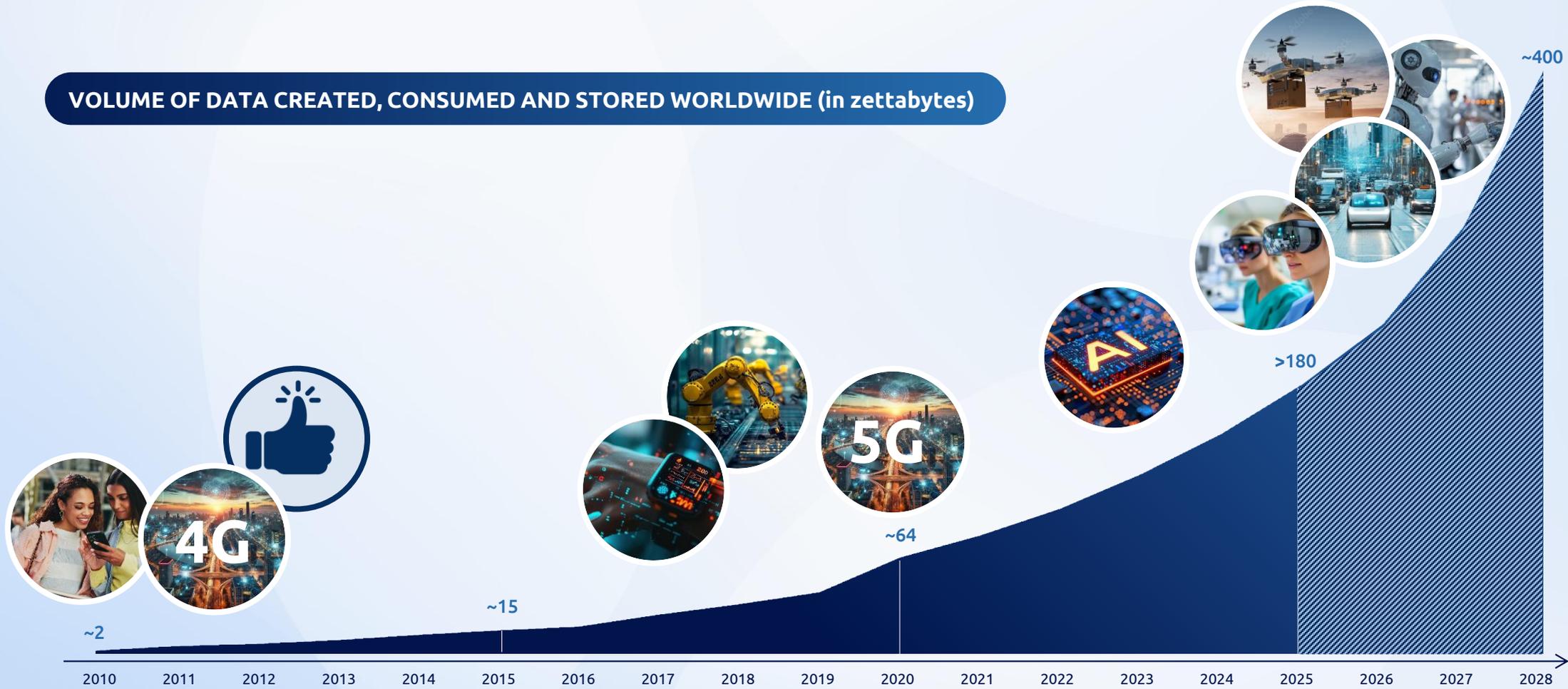
Source: Apple, Samsung, Meta Ray-Ban



NEW HABITS DRIVING EXPONENTIAL GLOBAL DATA GROWTH

CLOUD, HYBRID WORK, STREAMING, AUTONOMOUS VEHICLES, IoT, WEARABLES...

VOLUME OF DATA CREATED, CONSUMED AND STORED WORLDWIDE (in zettabytes)



Source: IDC, statista.com



REDEFINING THE RF FRONT END REQUIREMENTS

A STRUCTURAL TRANSFORMATION PUSHING THE LIMITS OF CONNECTIVITY PERFORMANCE & DIFFERENTIATION

GenAI + extension to new form factors

Transforming mobile networks from content delivery platforms into real-time distributed AI systems

ENHANCED CONNECTIVITY

Facing increased uplink & continuous downlink traffic



Low latency



Higher uplink data rates



Higher downlink data rates



Extended spectrum

AI at the EDGE

Increasing constraints on thermal management & footprint optimization



Real-time processing



Increased power consumption



Extended memory & NPU content

Increased BoM, enhanced thermal management & footprint optimization requirements

Source: Soitec

AI x CONNECTIVITY – MOVING TO AN ALL-CONNECTED WORLD

5G PERFORMANCE vs 4G



x100
NETWORK
CAPACITY



x10
SPEED



x10
FASTER
RESPONSE TIME



x10
CONNECTED
DEVICES

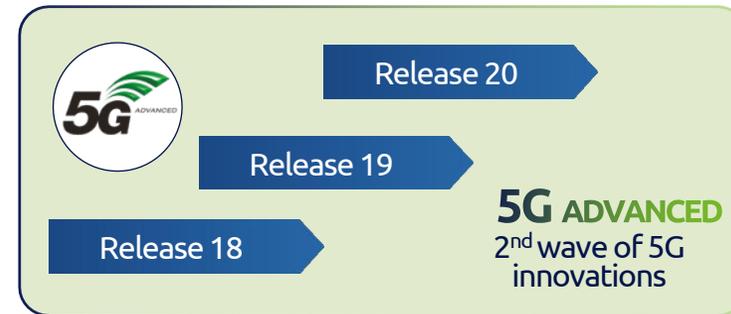
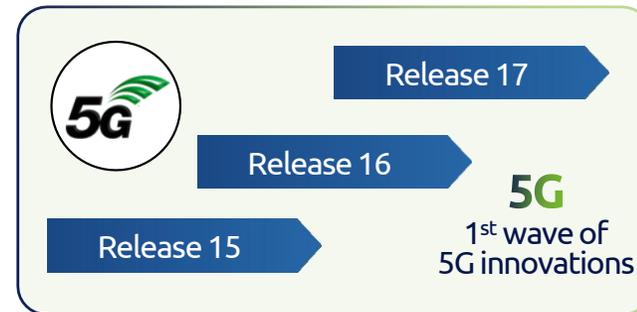


x10
LESS ENERGY
PER DATA

5G to 6G – PREPARING FOR A NEW ERA

5G ROADMAP EXTENDS FOR 10+ YEARS

Driving innovation to enhance smartphones and transform other industries



Continued innovation for new vertical deployments, use cases, and spectra



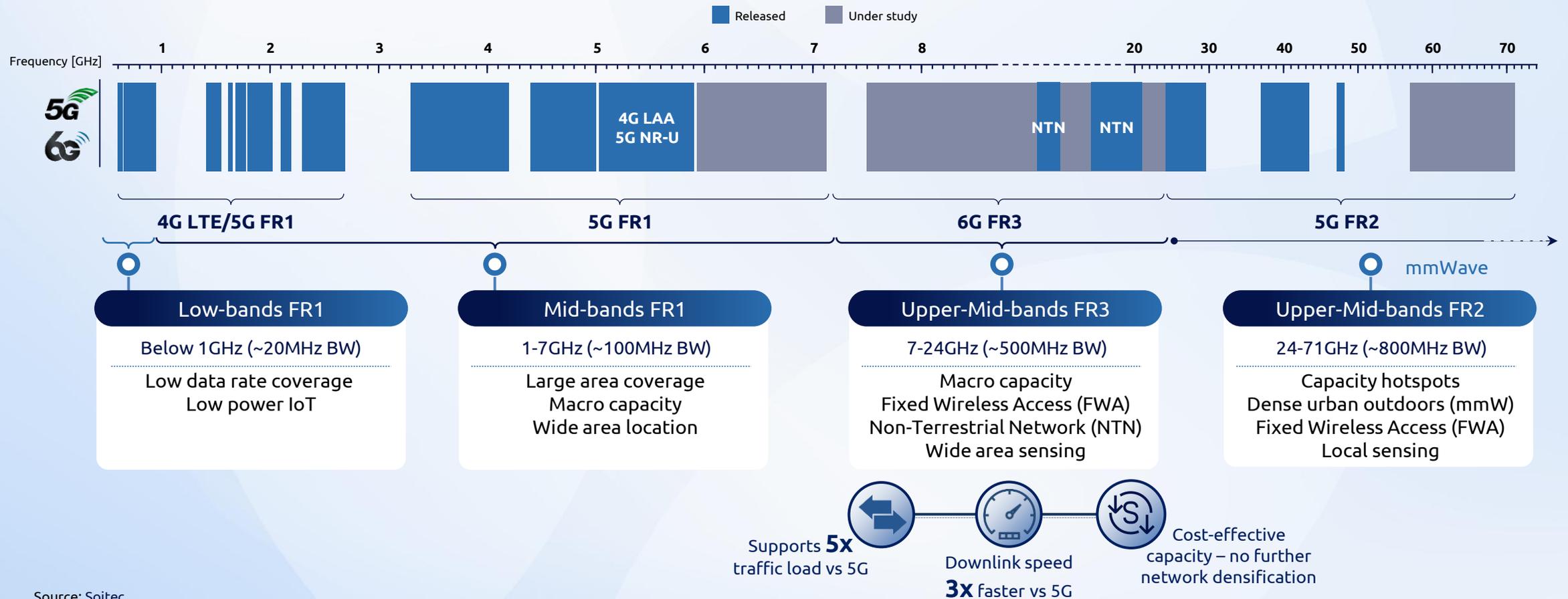
Source: Qualcomm, Ericsson



AI x CONNECTIVITY – MORE BANDS TO ACCOMMODATE GROWING DATA TRAFFIC

MAXIMIZING MULTI-BAND UTILITY: FOR EACH BAND, A USE CASE

Over the last 10 years, mobile data traffic has more than doubled on average every second year

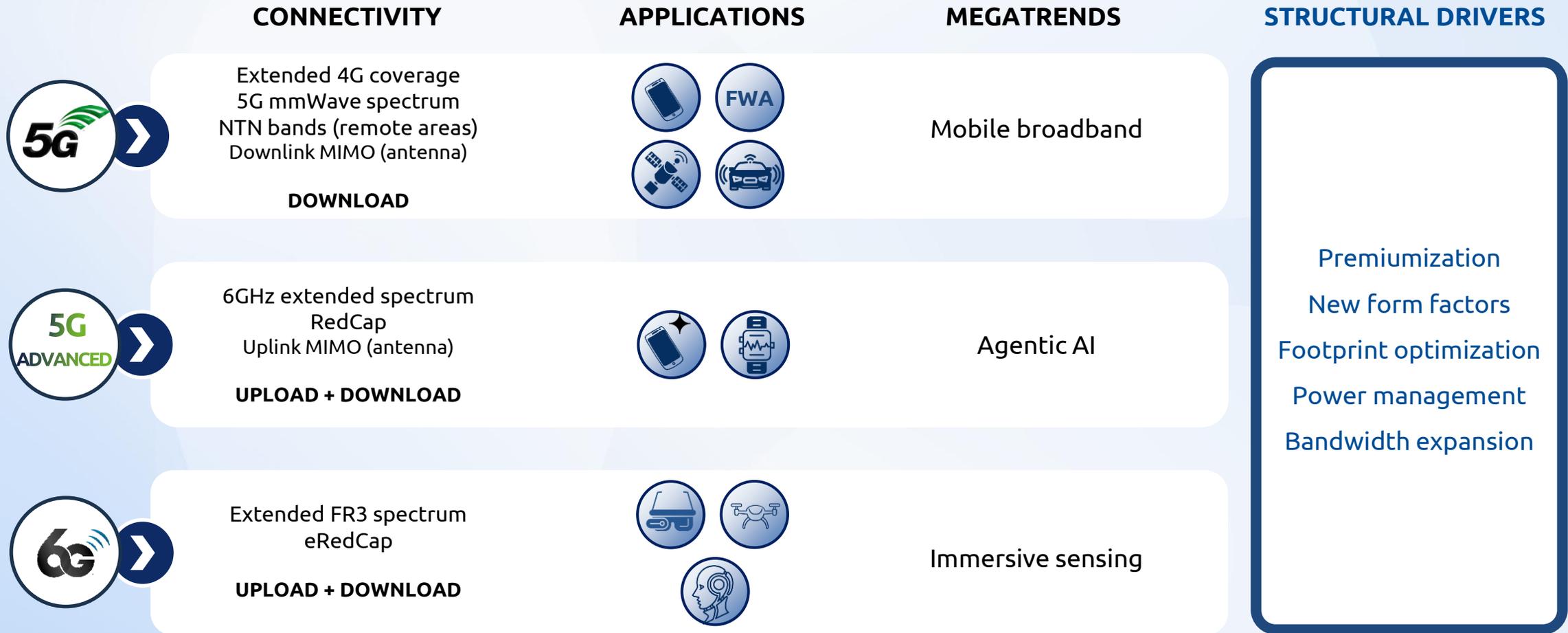


Source: Soitec



AI x CONNECTIVITY – SCALING NETWORK CAPABILITIES TO MEET MULTIMODAL DEMAND

NETWORK EVOLUTIONS BEYOND MOBILE BROADBAND, A MULTI-YEAR TAILWIND



Source: Soitec

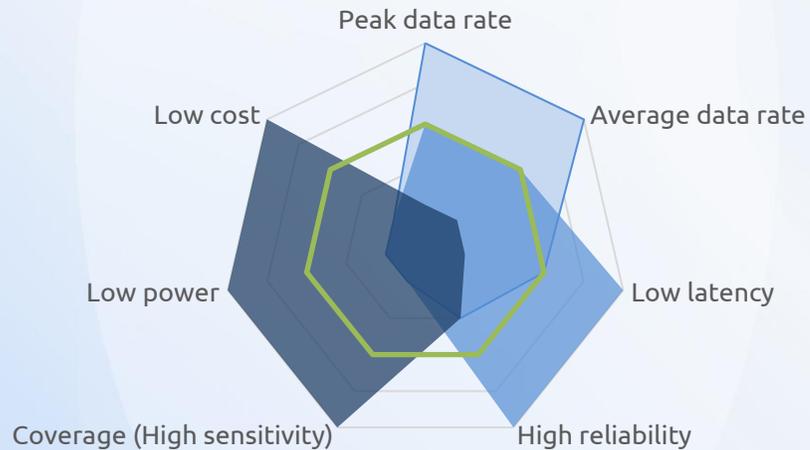


5G RedCap – EXPANDING 5G PENETRATION TO ADVANCED WEARABLES

MAKING 5G ACCESSIBLE & COST-EFFECTIVE, TOWARD A MORE CONNECTED WORLD

BALANCING PERFORMANCE, COST & POWER

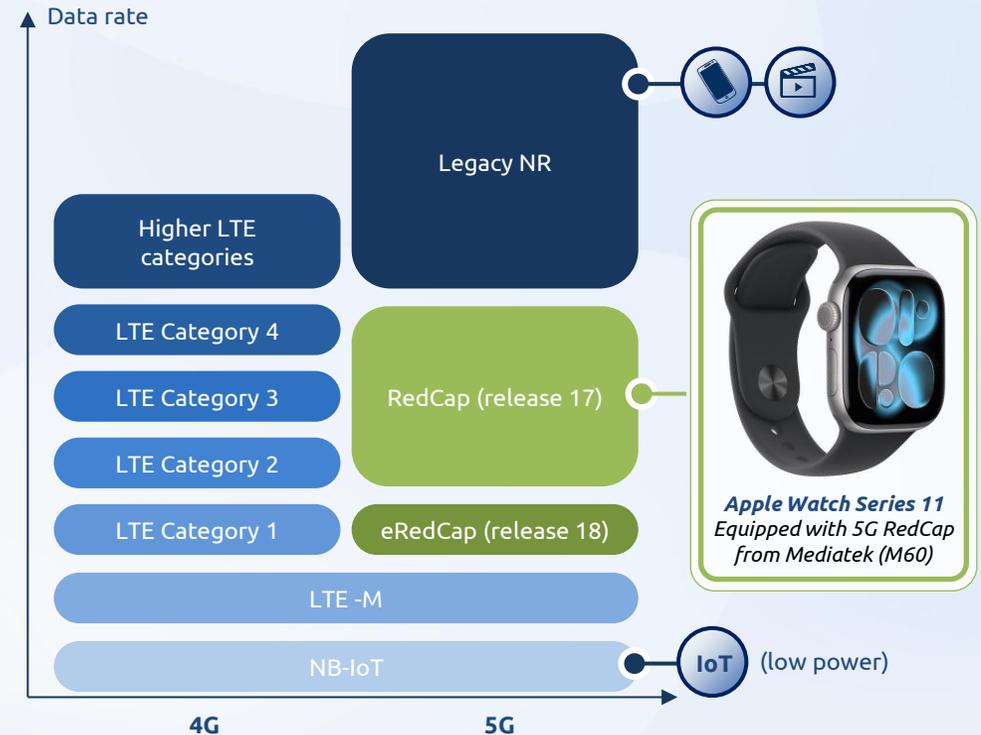
Simplifying RF complexity, reducing power consumption & cost to address advanced wearables & industrial efficiency



- eMBB Enhanced Mobile Broadband – 4G evolution (much faster & higher capacity)
- uRLLC Ultra-Reliable Low Latency Communications – typically used in AV, robotics
- mMTC Massive Machine Type Communication – designed for IoT
- RedCap Reduced Capacity – for advanced wearables

BRIDGING THE GAP BETWEEN HIGH-SPEED 5G & LOW-POWER IoT

eRedCap (R18) further simplifies RF complexity and reduce power consumption to extend 5G penetration to mid-tier advanced wearables



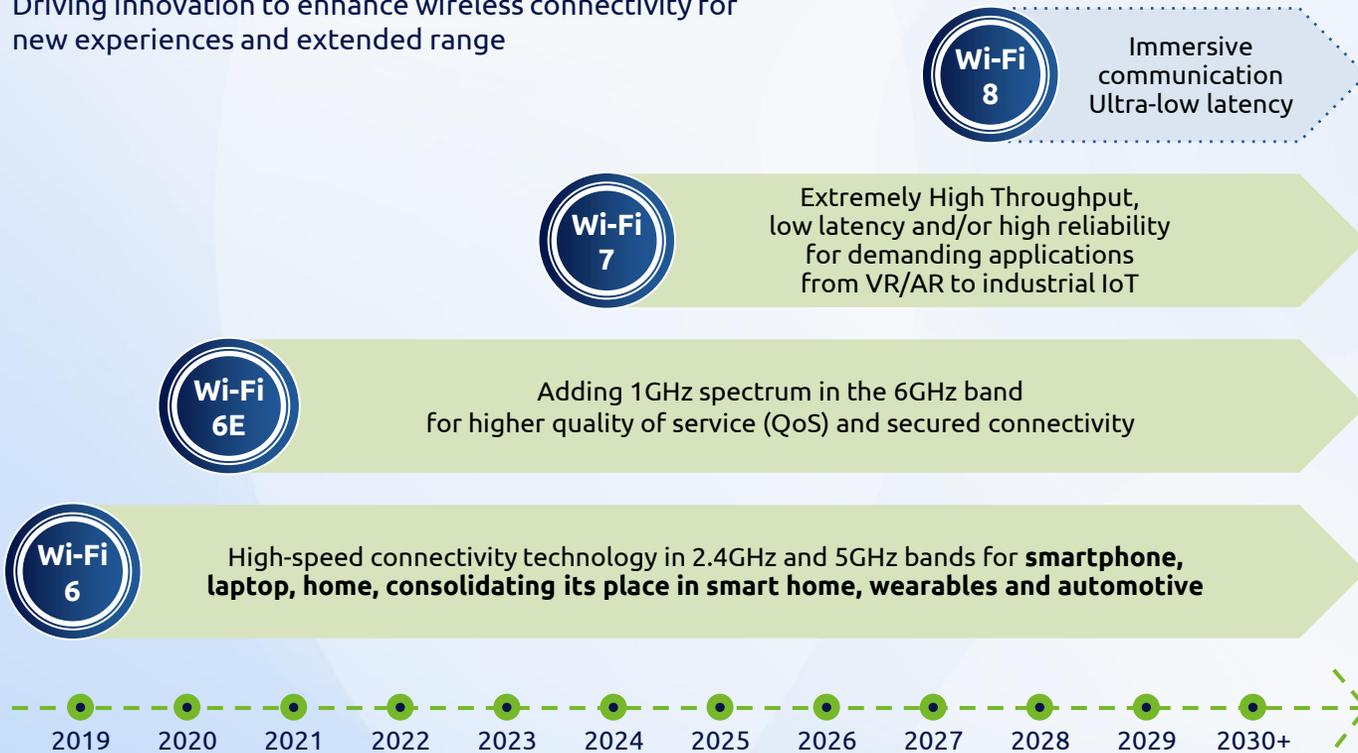
Source: GSMA 2025, Navian 2025

AI x CONNECTIVITY – ENHANCING Wi-Fi PERFORMANCE

ENABLING GREATER USER EXPERIENCES

Wi-Fi 6 / 6E / 7 pave the way for new wireless connectivity
 Wi-Fi 8 is on the way

Driving innovation to enhance wireless connectivity for new experiences and extended range



Wi-Fi FRONT-END-MODULE SEMICONDUCTOR MARKET



Source: Soitec



EXPANDING MOBILE COMMUNICATIONS, ENVIRONMENTS

FIXED WIRELESS ACCESS (FWA)



Last-mile technology with fiber-like data speeds via 5G



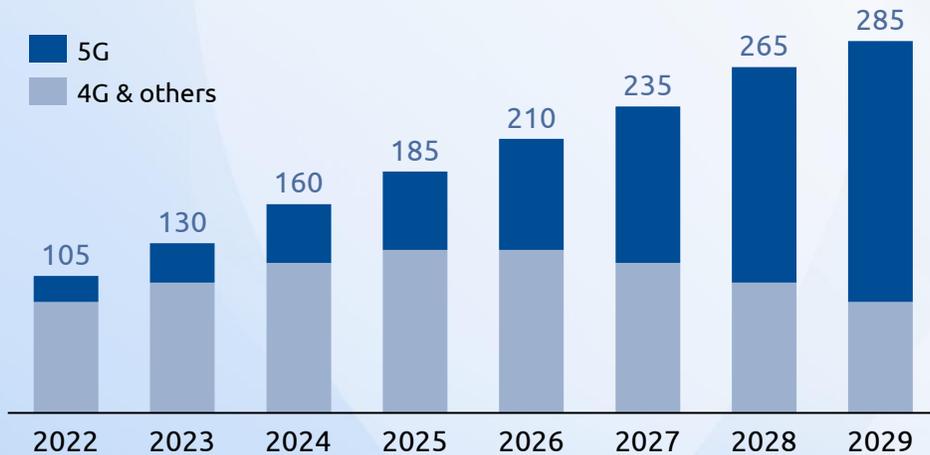
New indoor opportunities (smart homes, factories, cloudification...)



Virtual lag-less experiences

FWA connections (millions)

Ericsson expects FWA data traffic at the end of 2025 to represent >25% of global mobile data traffic and is projected to grow by a factor of > 3 by the end of 2031



Source: Yole, Ericsson Mobility Report 2025

ACROSS HOMES, ENTERPRISES & REMOTE

NON-TERRESTRIAL NETWORK (NTN)



New NTN bands enabling global coverage



Relies on fully integrated SoC solutions



Requires low energy power consumption solutions

Smartphones with satellite connectivity (Mu)

Yole expects all new iPhones to be equipped with a satellite chipset at least until 2029



ENGINEERED SUBSTRATES OPPORTUNITIES

SMARTPHONE MARKET CHALLENGED AMIDST MEMORY SHORTAGE

5G PENETRATION MODERATE GROWTH

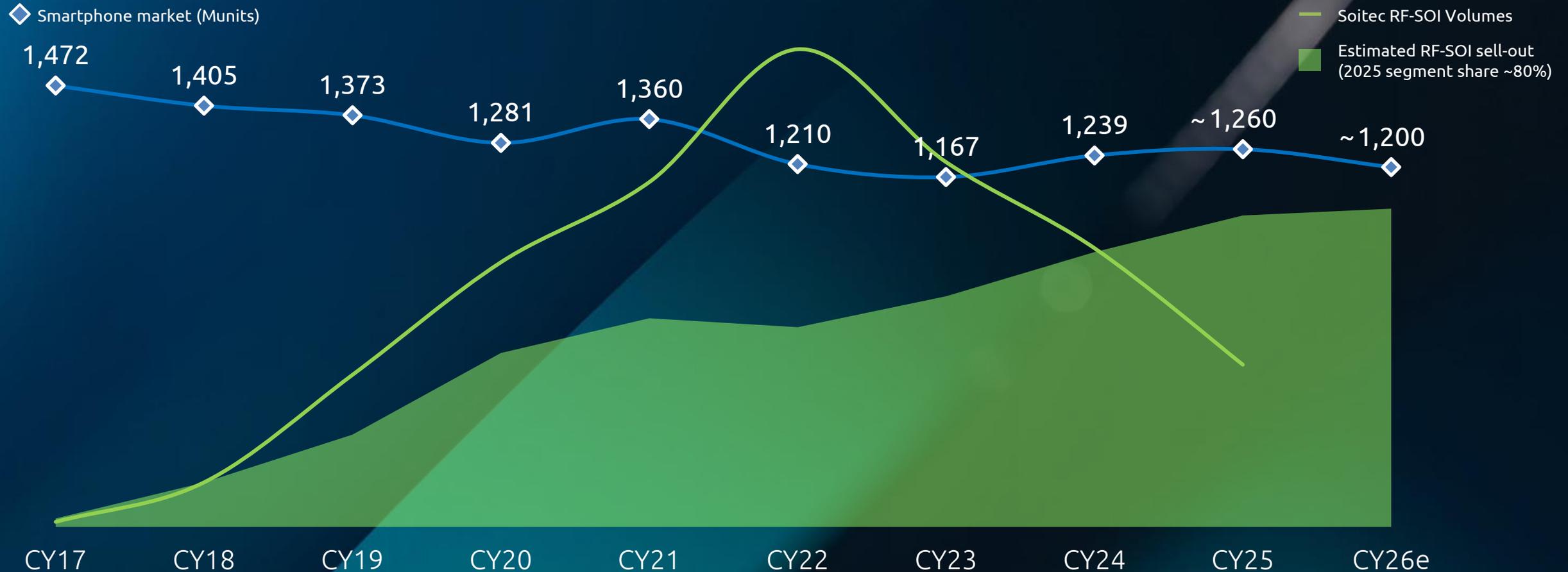


Source: IDC, Soitec



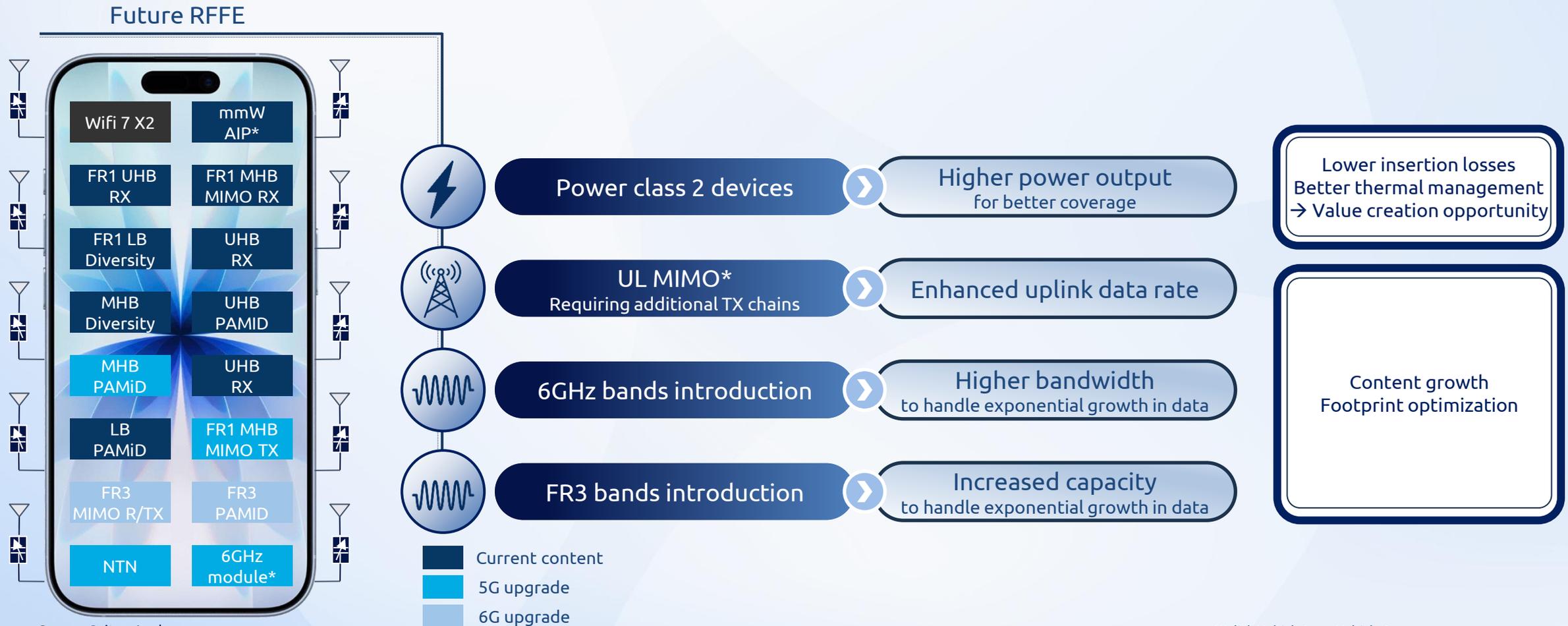
CUSTOMER INVENTORIES HEADING IN THE RIGHT DIRECTION

SIGNIFICANT UNDERSHIPMENT TO SUPPORT CUSTOMER INVENTORY CORRECTION



Source: Soitec

RFFE EVOLUTION – THE “UPLINK FIRST” ARCHITECTURE TO SUPPORT INCREASING DATA TRAFFIC DRIVEN BY AI DEMAND



Source: Soitec, Apple

*Uplink Multiple Input Multiple Output



WIRELESS CONNECTIVITY IN SMARTPHONES

A COMPREHENSIVE OFFER FOR Sub-6GHz & mmWave FRONT-END MODULES

RF-SOI
For highly efficient mobile communications

POI
High performance 5G filters

FD-SOI
Integrated technology

RF-GaN
High-performance power amplifiers

TODAY'S SMARTPHONE: MORE EFFICIENT, LOWER POWER CONSUMPTION, SMALLER FOOTPRINT

	4G / 5G Sub-6GHz	5G mmWave	Wi-Fi & UWB
POWER AMPLIFIER (PA)		● ●	●
LOW NOISE AMPLIFIER (LNA)	●	● ●	●
SWITCH	●	●	●
ANTENNA TUNER (AT)	●		●
FILTER	●		●
ENVELOPE TRACKER (ET)	●		●
PHASE SHIFTER		● ●	●
SYSTEM ON CHIP (SoC)		●	●
INTEGRATED FRONT-END	●	●	● ●

● RF-SOI ● FD-SOI ● POI ● RF-GaN

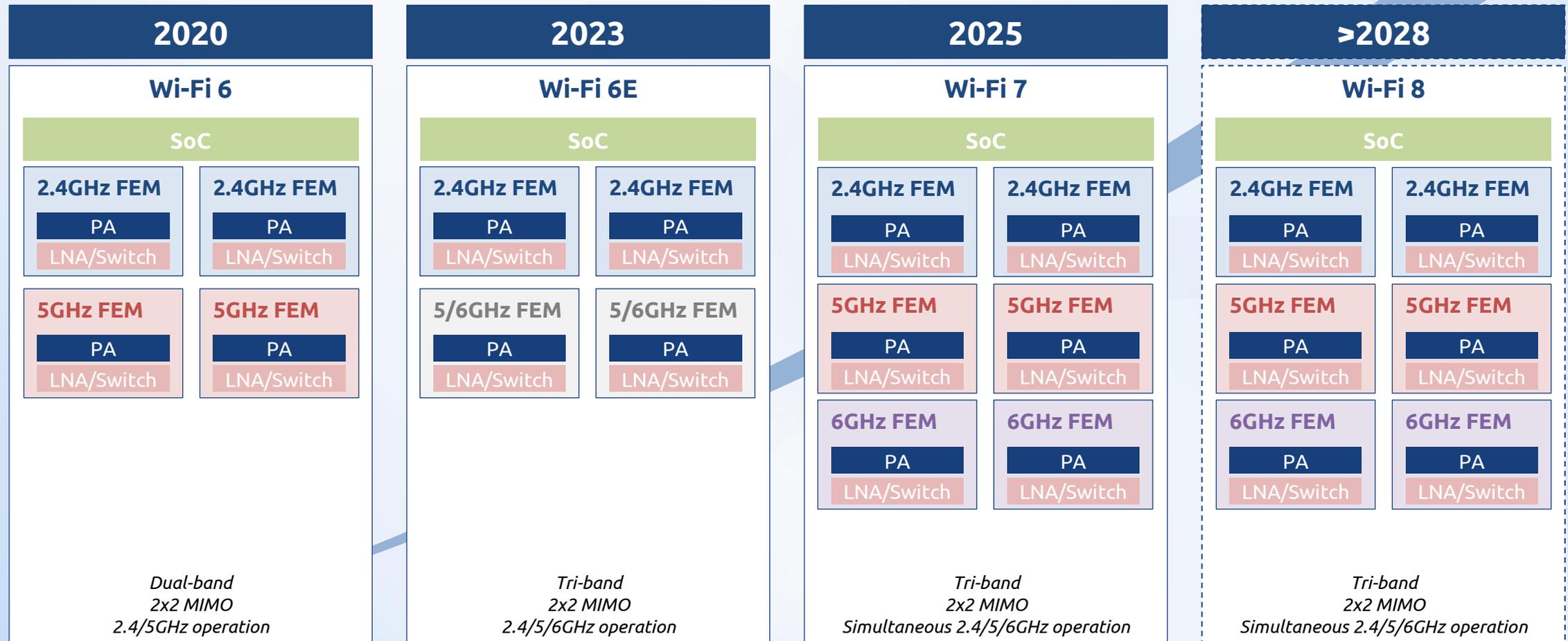
TOMORROW'S SMARTPHONE – MORE DATA, MORE BANDS: ADDITIONAL CONTENT TO THE FRONT-END MODULE

	5G	5G Advanced	6G
mmW ANTENNA IN PACKAGE	●	●	●
MIMO UHB	● ●	● ● ●	● ● ●
MIMO MB/HB	● ● ●	● ● ●	● ● ●
MIMO LB	● ● ●	● ● ●	● ● ●
NTN SOS & VOICE	● ●	● ●	● ●
NTN DATA		● ●	● ● ●
MIMO NEW 6GHz BANDS		● ● ●	
MIMO FR3			● ● ● ●



Wi-Fi 7/8 – FRONT END MODULE TRANSITION

UNLEASHING Wi-Fi FULL POTENTIAL WITH HIGHER CONTENT



Source: Yole 2024, Soitec consolidation



WIRELESS CONNECTIVITY IN AUTOMOTIVE



INFOTAINMENT in-vehicle

- Internet services
- Navigation system
- Screen mirroring
- Hands free voice
- Multimedia streaming



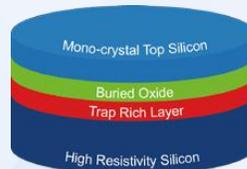
TELEMATICS cloud ↔ vehicle satellite ↔ vehicle

- OTA Update
- Vehicle location
- Optimum routing
- Internet access
- Fleet utilization
- Media services



ENVIRONMENT V2x

- Dynamic traffic signage
- Connection to home
- Pedestrian warning
- Driver assistance
- Remote control
- Keyless access



RF-SOI
Extended High performance RFFE
for connectivity,
C-V2X & 5G in automotive

FD-SOI
Extensive SoC solution
from connectivity to MCU/PMU
edge computing



Source: Soitec



WIRELESS CONNECTIVITY IN SMART DEVICES

ENABLING WIRELESS FUNCTIONALITIES AT LOW POWER CONSUMPTION

WIRELESS MODULES

MAINSTREAM

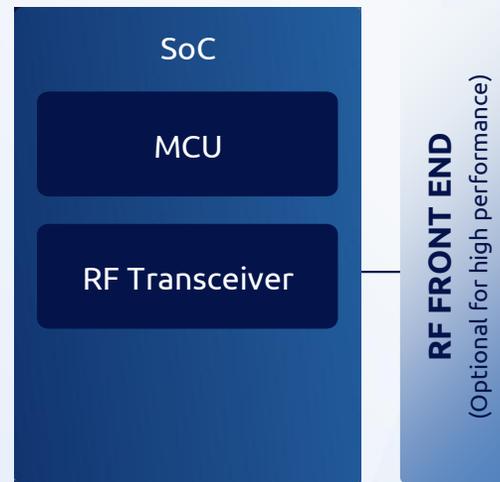
with integrated RFFE and low power consumption



FD-SOI

HIGH END

with externalized RFFE and extended RF performances

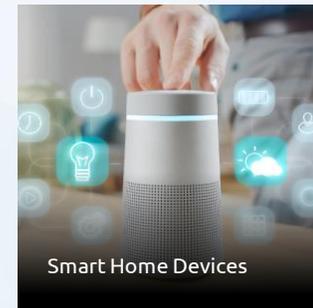


FD-SOI

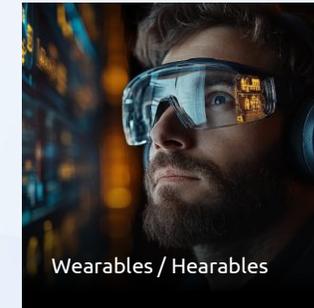


RF-SOI

POWER EFFICIENT WIRELESS SOLUTIONS SUPPORTING A WIDE RANGE OF APPLICATIONS



Smart Home Devices



Wearables / Hearables



Smart Cities

SOI ENGINEERED SUBSTRATES ENABLE BETTER SMART DEVICES



BATTERY POWER SAVINGS

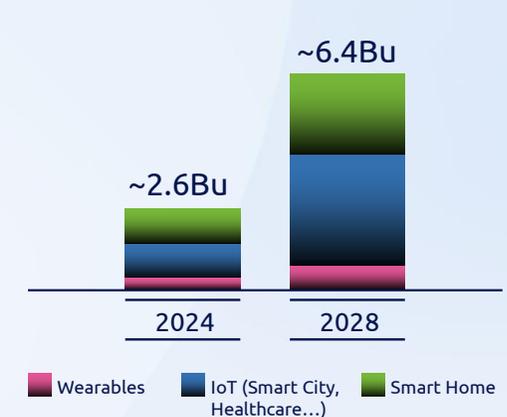


INTEGRATION FROM SOC TO MODULE



SIGNAL INTEGRITY WITH MULTI CONNECTIVITY PROTOCOLS

CONNECTIVITY WIRELESS SMART DEVICES



Source: ABI, 2024



AI SMART GLASSES – ENABLING STANDALONE AR WITH ENGINEERED SUBSTRATES

FROM SMARTPHONE COMPANION TO STANDALONE AR CONNECTIVITY

TODAY: THE SMARTPHONE COMPANION



Meta Ray-Ban Display

Compact form factor / Light
Wi-Fi / Bluetooth connectivity
 Processing capability
 Long battery life

NEXT-GENERATION: ENHANCED CONNECTIVITY

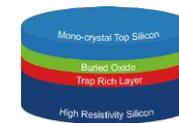


RayNeo X3 Pro

Compact form factor / Light
Wi-Fi / Bluetooth connectivity
+ 4G LTE and 5G RedCap
 Processing capability
 Long battery life

SOITEC CONNECTIVITY SOLUTIONS

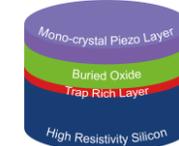
RF-SOI



Best-in-class RF performance
 Lower latency for real-time applications
 Reduced power consumption
 Better thermal management
 Smaller footprint



POI



Optimal solution for advanced SAW filters
 Can operate across the entire spectrum
 Improved coupling
 Lower insertion losses
 Better thermal management
 Better integration

SOITEC COMPUTING SOLUTION

FD-SOI



Energy efficiency / low-leakage
 Always-on / on-demand performance
 Low power consumption
 Greater integration / compacity

Source: Meta, NXP, RayNeo, Soitec

TEARDOWNS CONFIRM SOITEC CONTENT IN ALL 5G SMARTPHONES

AVERAGE ACTUAL SOITEC CONTENT PER SMARTPHONE (mm²)

Average of All smartphones

- RF-SOI
- POI
- FD-SOI
- GaN



Source: Soitec



SOITEC TECHNOLOGY LEADERSHIP ACCELERATES AI x CONNECTIVITY CONVERGENCE

INNOVATION TO SUPPORT CONTENT GROWTH AND VALUE CREATION

ENGINEERED SUBSTRATES ENABLE NEXT-GENERATION DEVICES

Enhanced connectivity
& user experience



AI & ML
5G NR-U (6GHz)
5G FR3 (10-20GHz)
Wi-Fi 7

UWB
NTN 3GPP & proprietary
sub-6GHz & mmWave

Enabling new technology
differentiation for our customers



3D-stacking
Footprint optimization
(die shrink)
Technology scaling
(higher frequencies)

Foundry yield
improvement
Advanced RF
Performances

Enabling
new devices

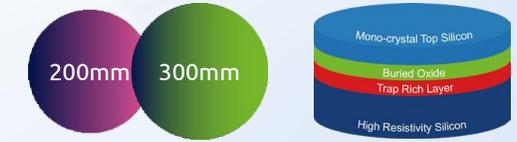


Form factor: increasing foldable phone market
share leads to increasing antenna integration
challenges

New devices (smart glasses, wearables)
requiring optimized footprint

RF-SOI

RF-SOI EMBEDDED IN 100% OF 5G SMARTPHONES



RF-SOI EXPANDING LEADERSHIP INTO NEW 5G VERTICALS



5G Communications

Automotive & Industry 4.0

AR / VR

Fixed Wireless Access

OUR RF-SOI SUBSTRATES ENABLE



5G Connectivity Enhancement

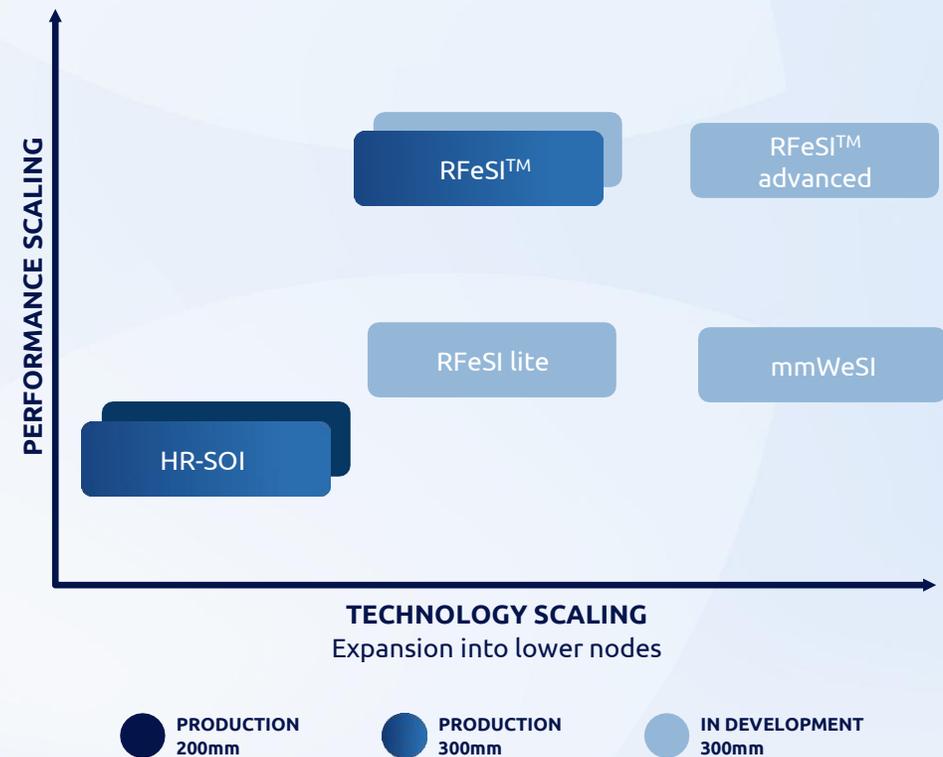


Battery Power Saving



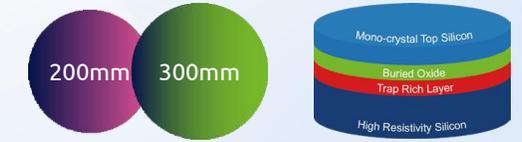
Optimized Footprint with RFFE Integration

RF-SOI ROADMAP



RF-SOI 300mm ACCELERATED TRANSITION

SUPPORTING FOUNDRIES ROADMAP & ENABLING DIFFERENTIATION



"This collaboration with Soitec shows our commitment to ensure a continuous supply of high-performance RF-SOI solutions that meet our customers' fast evolving needs"



"Leveraging our strong partnership with Soitec, UMC's innovative 3D IC solution for RF-SOI has generated significant interest from customers as they seek to integrate more RF components in 5G-enabled wireless devices"



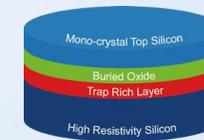
"The unique advantages of Tower's RF-SOI technology have enabled Broadcom to design and bring to market a set of compact, high-performance FEMs for Wi-Fi 7 mobile applications"



Source: Yole, Soitec, Company website



300mm ACCELERATES TECHNOLOGY DIFFERENTIATION AND UNLOCKS BETTER ECONOMICS

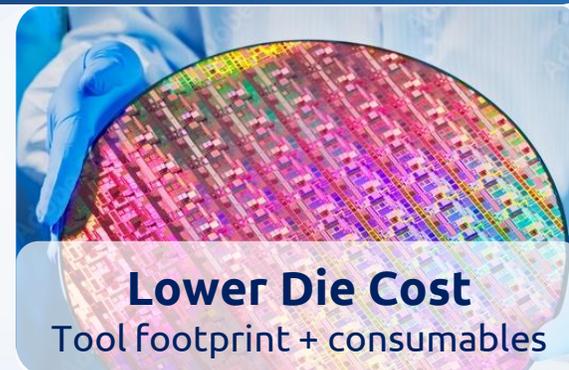


TECHNOLOGY DIFFERENTIATION



+ **Compatibility with lithography tools**
For leading edge applications

BETTER ECONOMICS



INNOVATION IN 300mm RF-SOI ACCELERATING THE AI x CONNECTIVITY CONVERGENCE LEADING THE RF-SOI EVOLUTION

GenAI + extension to new form factors

Transforming mobile
networks from content
delivery platforms into real-
time distributed AI systems

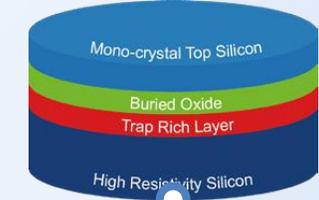


FOUNDRIES



- Advanced node processing (CMOS sub-45nm)
- Enhanced signal integrity / linearity to enable 5G advanced / 6G
- Reduced insertion losses to optimize power consumption
- Footprint optimization with 3D integration (3D IC by UMC x Soitec)

300mm RF-SOI

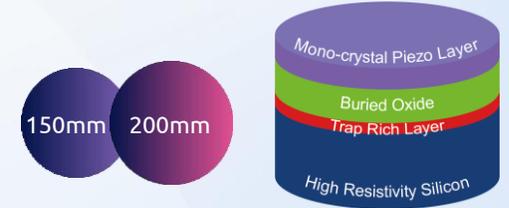


- Superior uniformity across 300mm
- Ensure overlay robustness
- Enhanced trap-rich performance
- Improved high resistivity Si layer
- Improved BOX performance
- Roadmap to enable 3D RF-SOI



POI

POI FOR ADVANCED RF FILTERS ADOPTED BY MAIN OEMs



iPhone 16e



Google Pixel 9
Google Pixel 9 Pro



Google Pixel 9 Pro Fold



Samsung Galaxy Z Flip5



Ray-Ban Meta

OUR POI SUBSTRATES ENABLE



Better Filter Performance



Battery Power Saving



Optimized Filter BOM Footprint

Source: Samsung, Google, Apple, Ray-Ban

POI ROADMAP



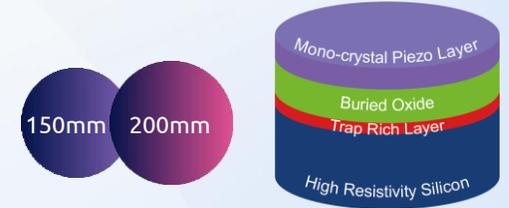
● PRODUCTION 150mm ● IN DEVELOPMENT 150mm ● IN DEVELOPMENT 200mm

LB: Low Band (0.6-1GHz), MHB: Mid-High Band (1.4-2.7GHz), UHB: Ultra High Band (>3.3GHz)
LN: Lithium Niobate on Insulator, LT: Lithium Tantalate on Insulator



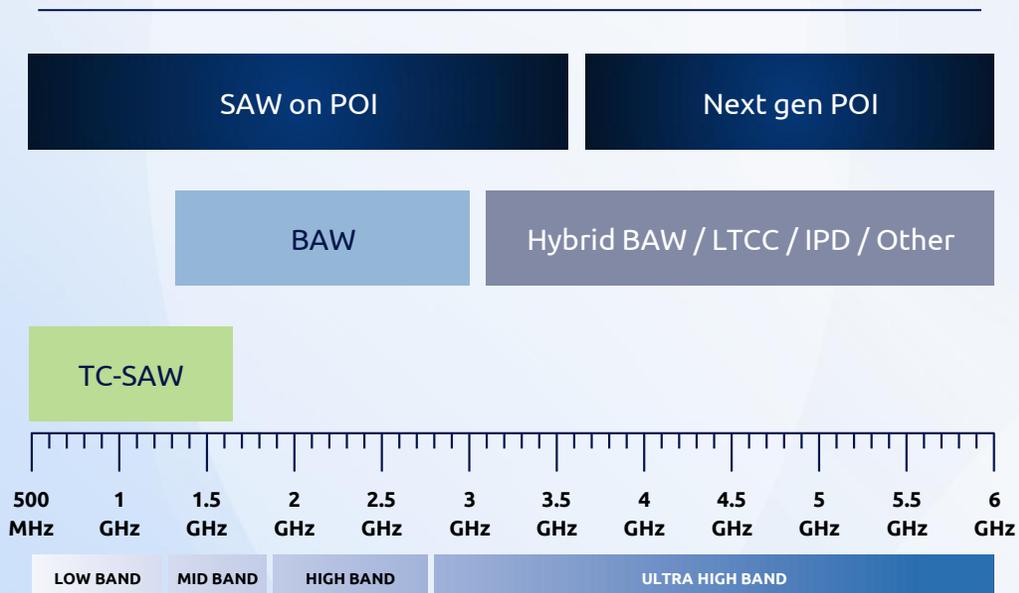
POI

WHY POI?



SAW-ON-POI CAN OPERATE ACROSS THE WHOLE FREQUENCY SPECTRUM

Enabling transition to higher bands



SAW-ON-POI ADDRESSES ALL 5G FILTER NEEDS

From higher selectivity to lower insertion losses, enhanced frequency stability and easier multiplexer integration



	SAW	TC-SAW	BAW	SAW-on-POI
Substrate	Piezo (non-POI)	Piezo (non-POI)	Piezo (non-POI)	POI
Quality Factor	=	-	+	+
Coupling factor	=	-	=	+
Temperature Compensation	=	+	=	+
Process simplicity	=	-	-	=
Integration	=	=	=	+



POI

STRONG VALUE FOUNDATION FOR MARKET EXPANSION

POI customer testimony

“
Tier #1 US: a **“Performance play”**
Tier #1 US: *Soitec POI perform “better than TC-SAW”*
Tier #1 US: **“better Qmax than equivalent BAW technology”**
Tier#2 China: *Soitec POI is considered as a “reference”*
”



13 customers in Production



9 customers in Qualification



Engaged with all key players



Google Pixel 9 integrates POI from Qorvo & Skyworks

LEADING RF FILTER MANUFACTURERS INTEGRATE SOITEC POI FROM LOW- TO MID-HIGH BANDS

“
The trend towards using multilayer SAW filters is occurring in flagship smartphones like the Google Pixel 9. Yole Group has identified **piezoelectric on insulator (POI) SAW filters** in the Google Pixel 9 smartphone supplied by Qorvo and Skyworks.
”

Source: Yole, Google



INNOVATION IN POI – ADDRESSING INCREASINGLY COMPLEX RFFE

UPGRADING THERMAL MANAGEMENT PERFORMANCES & EXPANDING TO HIGHER FREQUENCIES

GenAI + extension to new form factors

Transforming mobile networks from content delivery platforms into real-time distributed AI systems

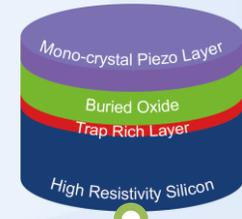


FILTERS



- Better thermal management to handle high power 5G signals
- Optimized footprint with extended multiplexing
- Reduced insertion losses for high power class (PC2) devices
- Extended frequency range & bandwidth to address a growing data load

POI



- Enhanced TCF management
- Thin layer engineering
- New LNO top layer roadmap
- Waveguide performance



FD-SOI

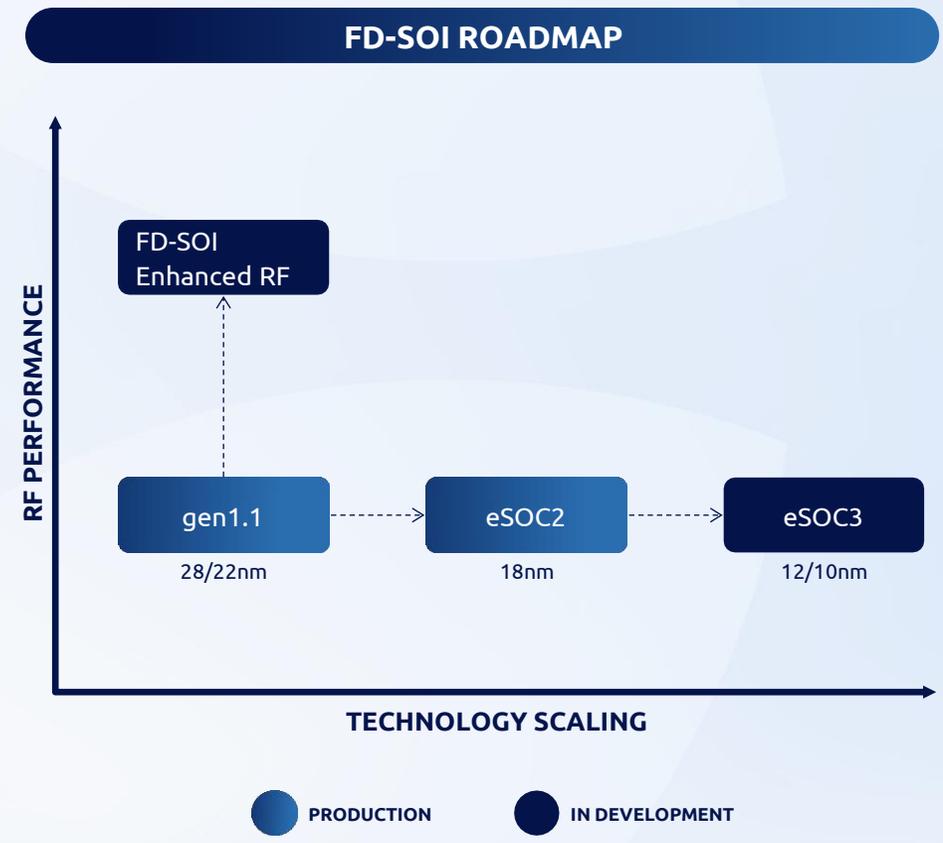
FD-SOI FOR mmWave ENDORSED BY MAJOR SMARTPHONE OEMs



OUR FD-SOI SUBSTRATES ENABLE

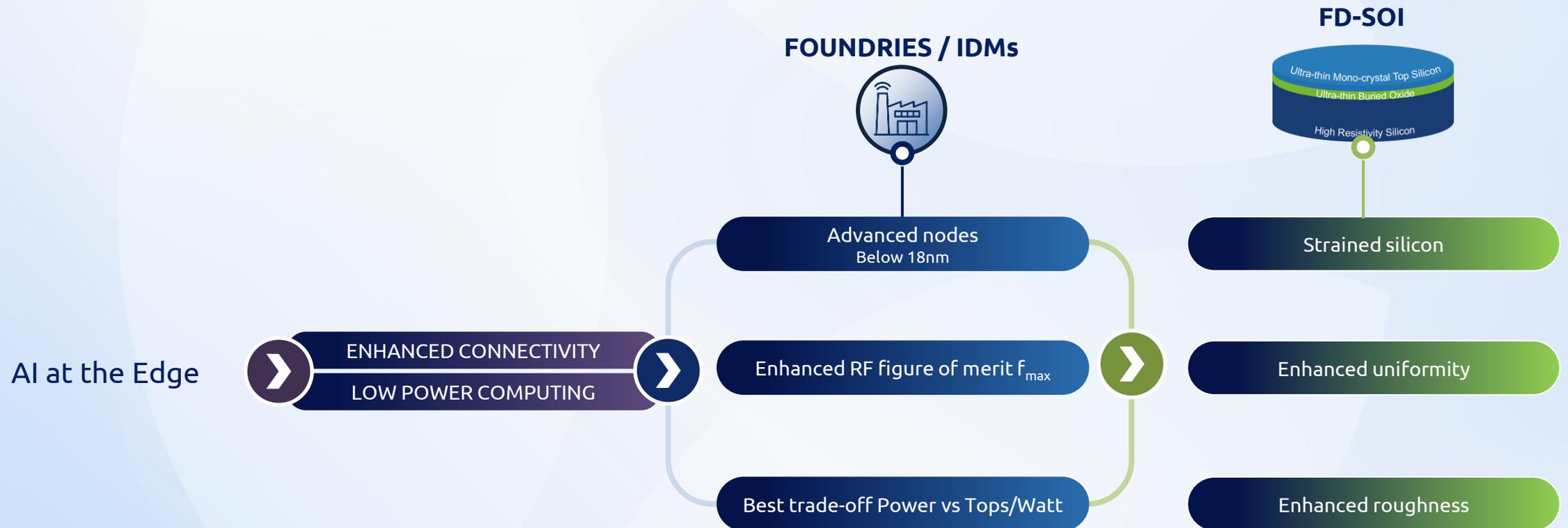
- High Quality & Extended 5G mmWave Link
- >10% Battery Power Saving
- Optimized Footprint with Digital Scaling

Source: Samsung, Google



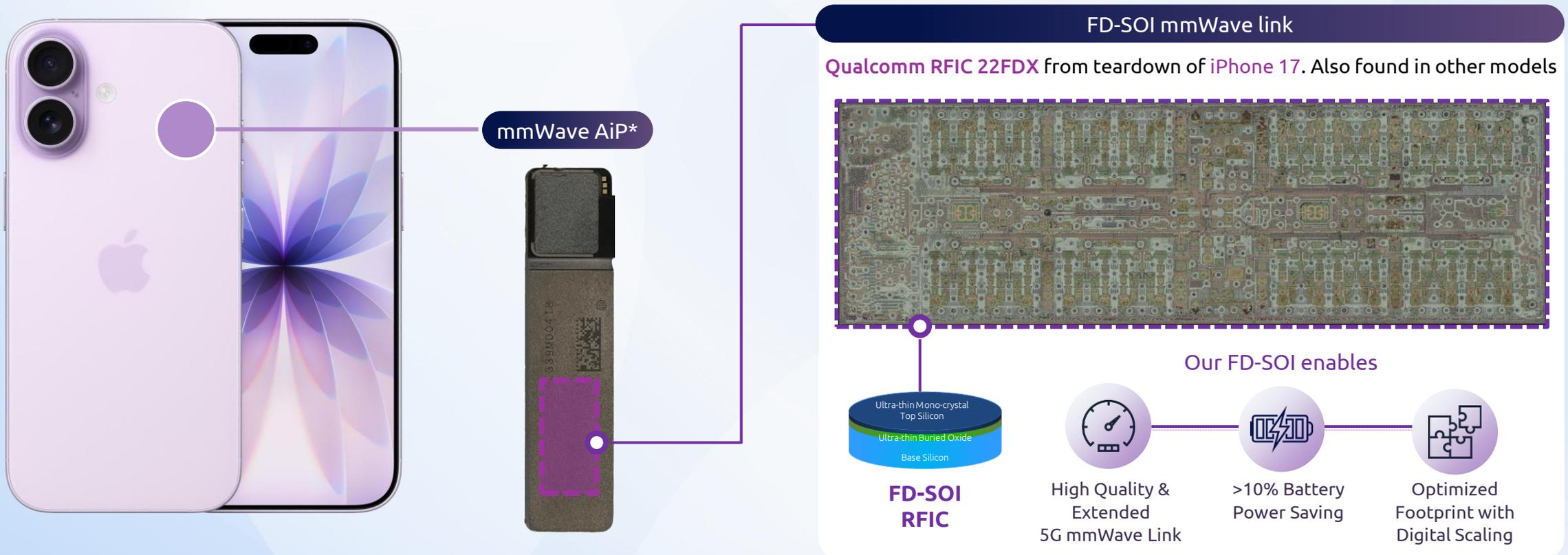
INNOVATION IN FD-SOI – TOWARDS 18nm NODE

ENABLING THE TRANSITION TO 18nm AND BEYOND



EXTENDING FD-SOI mmWave PENETRATION TO iPhone

Techinsights x Yole teardowns & analysis reveal the 5G mmWave antenna module in the iPhone 17, iPhone 17 Pro and iPhone 17 Pro Max relies on Soitec state-of-the-art FD-SOI



Source: TechInsights 2025, Yole, Soitec

*AiP: Antenna-in-Package

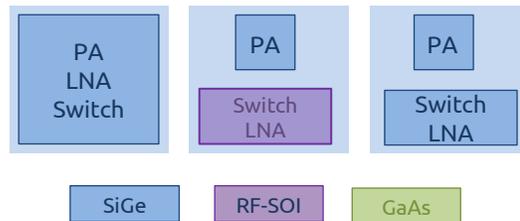


Wi-Fi: FROM A MULTI-DIE SOLUTION TO MONOLITHIC INTEGRATION WITH RF-SOI

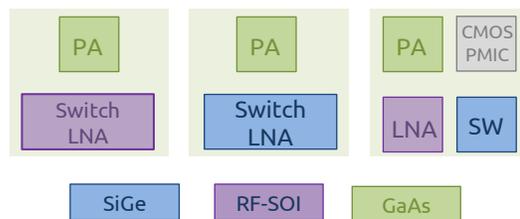
TEARDOWN OF GOOGLE PIXEL 9

From multi-dies Wi-Fi solution

SiGe based Wi-Fi die solution



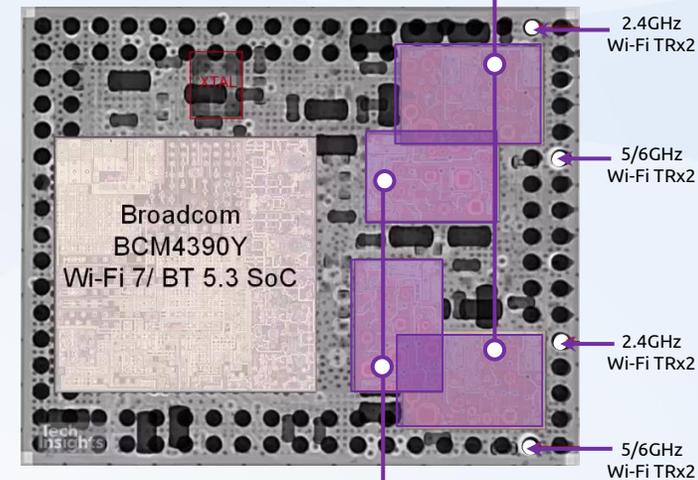
GaAs based Wi-Fi die solution



...to full RF-SOI die solution

USI G6-602650 Wi-Fi 7/BT 5.3 Module found in Google Pixel 9 Pro XL & others

Broadcom + Tower Semiconductor 5-7GHz RF-SOI PA+LNA+ Switch RFFE



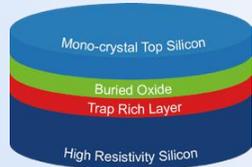
Broadcom + Tower Semiconductor 2.4GHz RF-SOI PA+LNA+ Switch RFFE

Source: Soitec

SOITEC EXTENDS ITS FOOTPRINT

KEY DESIGN-WINS ANNOUNCEMENTS OVER THE PAST 2 YEARS

300mm RF-SOI



POI



FD-SOI



 <p>New RF-SOI standard with Broadcom's Wi-Fi RFFE modules for next gen mobile applications</p>	 <p>New RF-SOI standard with Broadcom's WiFi RFFE modules for next gen applications</p>	 <p>Advanced 9SW platform to use Soitec's latest generation of 300mm RF-SOI</p>	 <p>3D IC antenna tuners in iPhone 17</p>	 <p>Design wins for full RFFE Wifi 7 RF-SOI</p>
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 <p>Google Pixel 9 & 10 integrate POI from Skyworks x Qorvo</p>	 <p>Multiple design wins for PAMID Chinese Android OEM Mid-End to High-End</p>	 <p>Multiple design wins in the iPhone 17</p>	 <p>Tier-1 US Fabless Move into volume production</p>
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 <p>5G mmWave design wins in Samsung S25 & Z Fold US modules</p>	 <p>Design wins for Wi-Fi 7 SoC transceiver premium android smartphone</p>	 <p>5G mmWave & envelope tracker design wins in the iPhone 17</p>	 <p>Design wins for MCU</p>
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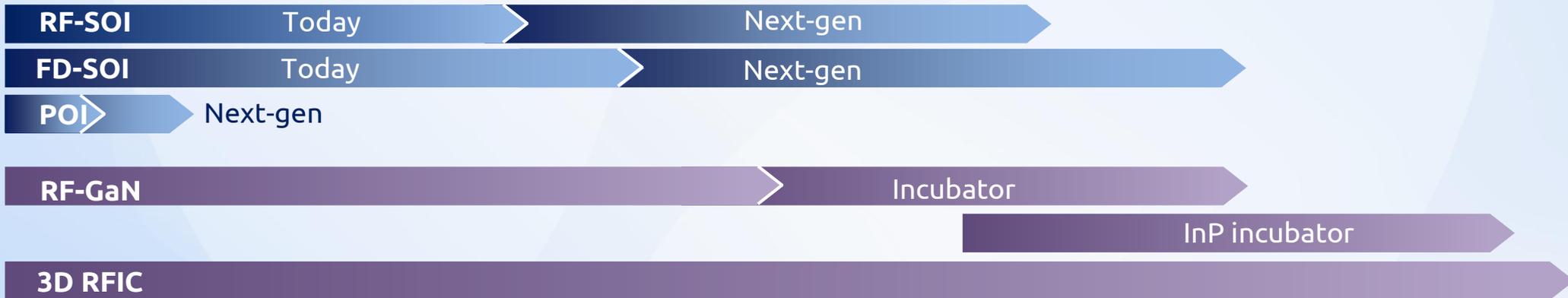


PERFORMANCE ALWAYS STARTS WITH HARDWARE

SOITEC PRODUCT ROADMAP EXPANDS ADDRESSABLE MARKET



soitec



Source: Qualcomm, Ericsson, Soitec





AI x CONNECTIVITY POWERED BY ENGINEERED SUBSTRATES

THANK YOU

4G LAA	4G License Assisted Access	LTCC	Low Temperature Co-fired Ceramic
4G LTE	4G Long-Term Evolution	MCU	Microcontroller Unit
5G NR-U	5G New Radio Unlicensed	MHB	Mid-High Band
AiP	Antenna-in-Package	NTN	Non-Terrestrial Network
BAW	Bulk Acoustic Wave	RFFE	RF Front-End
CPE	Customer Premises Equipment	SAW	Surface Acoustic Wave
FTTX	Fiber-to-Anything	SoC	System-on-Chip
FWA	Fixed Wireless Access	TC-BAW	Temperature Compensated BAW
IPD	Integrated Passive Devices	UHB	Ultra-High band
LB	Low Band	UWB	Ultra-Wide band
LNA	Low Noise Amplifier	UL MIMO	Uplink Multiple Input Multiple Output
		V2x	Vehicle-to-Everything